

MOSFETs Silicon N-Channel MOS (U-MOSVII-H)

# TPCC8067-H

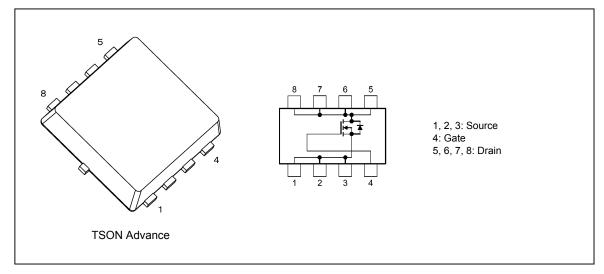
#### 1. Applications

- High-Efficiency DC-DC Converters
- Notebook PCs
- · Mobile Handsets

#### 2. Features

- (1) Small, thin package
- (2) High-speed switching
- (3) Small gate charge:  $Q_{SW} = 1.9 \text{ nC (typ.)}$
- (4) Low drain-source on-resistance:  $R_{DS(ON)} = 26 \text{ m}\Omega$  (typ.) ( $V_{GS} = 4.5 \text{ V}$ )
- (5) Low leakage current:  $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 30 \text{ V)}$
- (6) Enhancement mode:  $V_{th}$  = 1.3 to 2.3 V ( $V_{DS}$  = 10 V,  $I_D$  = 0.1 mA)

## 3. Packaging and Internal Circuit





#### 4. Absolute Maximum Ratings (Note) (Ta = 25°C unless otherwise specified)

Characterist	Symbol	Rating	Unit		
Drain-source voltage			$V_{DSS}$	30	V
Gate-source voltage			V <sub>GSS</sub>	-20/+20	
Drain current (DC)		(Note 1)	I <sub>D</sub>	9	Α
Drain current (pulsed)		(Note 1)	I <sub>DP</sub>	27	
Power dissipation	(Tc = 25°C)		P <sub>D</sub>	15	W
Power dissipation	(t = 10 s)	(Note 2)	P <sub>D</sub>	1.9	W
Power dissipation	(t = 10 s)	(Note 3)	P <sub>D</sub>	0.7	W
Single-pulse avalanche energy		(Note 4)	E <sub>AS</sub>	21	mJ
Avalanche current			I <sub>AR</sub>	9	Α
Channel temperature			T <sub>ch</sub>	150	°C
Storage temperature			T <sub>stg</sub>	-55 to 150	

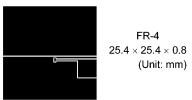
Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### 5. Thermal Characteristics

Characteristics				Max	Unit
Channel-to-case thermal resistance	(Tc = 25°C)		R <sub>th(ch-c)</sub>	8.33	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 2)	R <sub>th(ch-a)</sub>	65.7	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 3)	R <sub>th(ch-a)</sub>	178	°C/W

- Note 1: Ensure that the channel temperature does not exceed 150°C.
- Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1
- Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2
- Note 4:  $V_{DD}$  = 24 V,  $T_{ch}$  = 25°C (initial), L = 0.2 mH,  $R_G$  = 1.2  $\Omega$ ,  $I_{AR}$  = 9 A



FR-4 25.4 × 25.4 × 0.8 (Unit: mm)

Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

FR-4

 $25.4\times25.4\times0.8$ 

(Unit: mm)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



#### 6. Electrical Characteristics

# 6.1. Static Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±0.1	μА
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V	_	_	10	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	30	_	_	V
	V <sub>(BR)DSX</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = -20 V	15	_	_	
Gate threshold voltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.1 mA	1.3	_	2.3	
Drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 4.5 A	_	26	33	mΩ
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4.5 A		20	25	

## 6.2. Dynamic Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	690	_	pF
Reverse transfer capacitance	C <sub>rss</sub>		1	28		
Output capacitance	C <sub>oss</sub>		1	120	_	
Gate resistance	r <sub>g</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 5 MHz	-	3.4	5.1	Ω
Switching time (rise time)	t <sub>r</sub>	See Figure 6.2.1.		2.1	_	ns
Switching time (turn-on time)	t <sub>on</sub>		_	6.5		
Switching time (fall time)	t <sub>f</sub>		_	2.0	_	
Switching time (turn-off time)	t <sub>off</sub>		-	14	_	

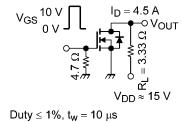


Fig. 6.2.1 Switching Time Test Circuit

# 6.3. Gate Charge Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus	$Q_g$	$V_{DD} \approx 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 9 \text{ A}$	_	9.5	_	nC
gate-drain)		$V_{DD} \approx 24 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 9 \text{ A}$	_	4.7	_	
Gate-source charge 1	Q <sub>gs1</sub>	$V_{DD} \approx 24 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 9 \text{ A}$	_	2.2	_	
Gate-drain charge	$Q_{gd}$		_	0.9	_	
Gate switch charge	Q <sub>SW</sub>		_	1.9	_	

# 6.4. Source-Drain Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Pulsed reverse drain current	(Note 5)	I <sub>DRP</sub>	_			27	Α
Diode forward voltage	•	V <sub>DSF</sub>	I <sub>DR</sub> = 9 A, V <sub>GS</sub> = 0 V	_	_	-1.2	V

Note 5: Ensure that the channel temperature does not exceed 150°C.



# 7. Marking

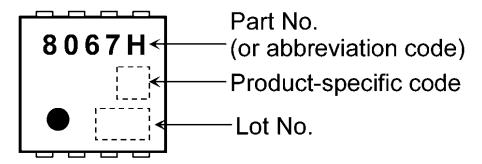


Fig. 7.1 Marking



## 8. Characteristics Curves (Note)

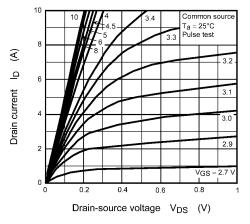


Fig. 8.1 I<sub>D</sub> - V<sub>DS</sub>

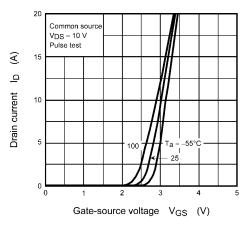


Fig. 8.3 ID - VGS

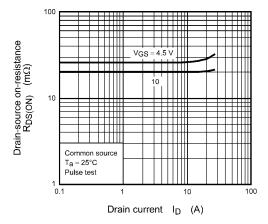


Fig. 8.5 R<sub>DS(ON)</sub> - I<sub>D</sub>

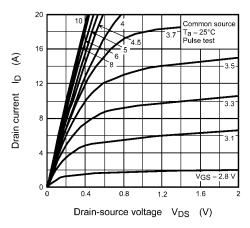


Fig. 8.2 I<sub>D</sub> - V<sub>DS</sub>

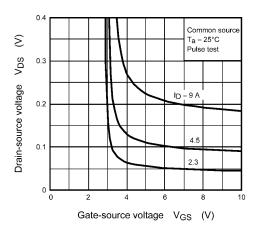


Fig. 8.4 V<sub>DS</sub> - V<sub>GS</sub>

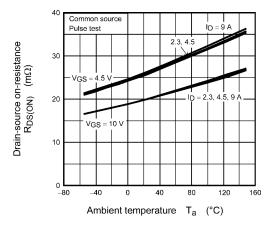


Fig. 8.6 R<sub>DS(ON)</sub> - T<sub>a</sub>

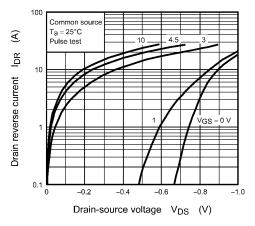


Fig. 8.7 IDR - VDS

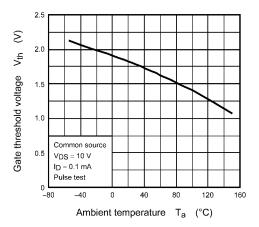


Fig. 8.9 V<sub>th</sub> - T<sub>a</sub>

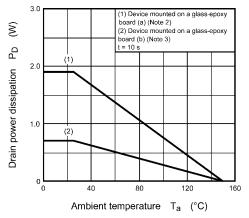


Fig. 8.11 P<sub>D</sub> - T<sub>a</sub> (Guaranteed Maximum)

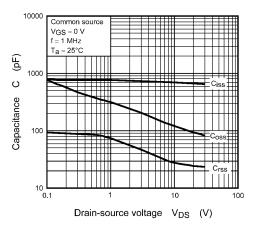


Fig. 8.8 Capacitance - V<sub>DS</sub>

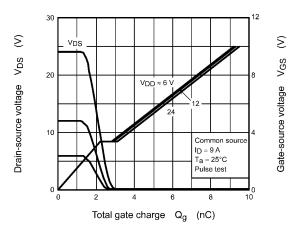


Fig. 8.10 Dynamic Input/Output Characteristics

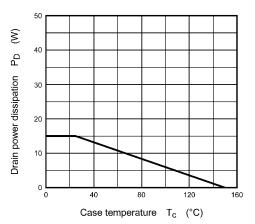


Fig. 8.12 P<sub>D</sub> - T<sub>c</sub> (Guaranteed Maximum)

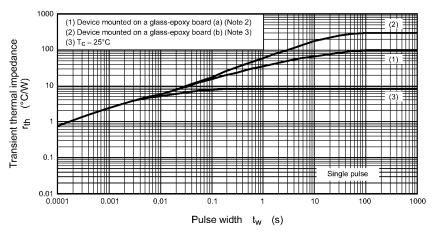


Fig. 8.13 r<sub>th</sub> - t<sub>w</sub> (Guaranteed Maximum)

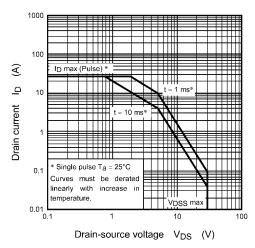


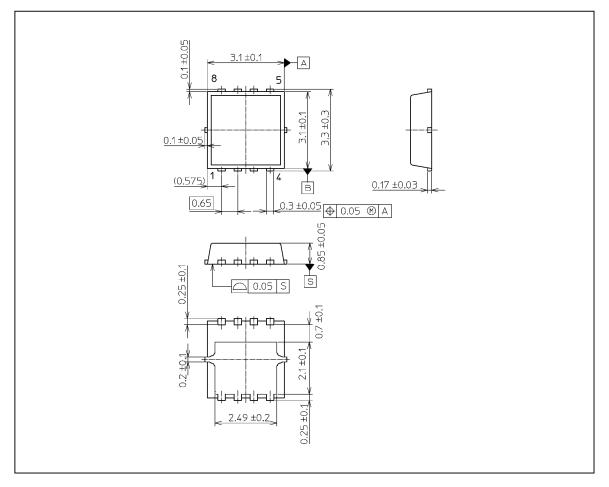
Fig. 8.14 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



## **Package Dimensions**

Unit: mm



Weight: 0.02 g (typ.)

Package Name(s)
TOSHIBA: 2-3X1S
Nickname: TSON Advance



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